

# **ENGIS<sup>®</sup> MICROTECH WAFER THINNING FIXTURE**

The Engis Microtech Wafer Thinning Fixtures are designed to control the thickness and parallelism of thin, fragile components.



**ADVANCED MATERIALS PRODUCTS**

FOR ADDITIONAL INFORMATION CONTACT THE ENGIS MICROTECH TEAM AT

[WWW.ENGISCA.COM](http://WWW.ENGISCA.COM)



# STANDARD FEATURES OF THE WAFER THINNING FIXTURE

- Designed to polish the Optical Product (Optical Fiber and Semiconductor Wafer)
- Capable of accepting configurations of various types of Parts Holding Fixtures and to process multiple Product in one cycle
- Contributes to decreasing manufacturing cost of Optical Product
- Controls the Pressure or Weight in the lapping process using the Tension of Spring and assists R&D for new products and polishing processes for various types of products.

## MACHINE SPECIFICATIONS

|                  |                            |
|------------------|----------------------------|
| MODEL            | HOJ-3                      |
| SUB JIG DIAMETER | MAX Ø83MM OUTSIDE DIAMETER |
| GAUGE            | USING THE 1UM              |
| WEIGHT CONTROL   | USING THE SPRING TENSION   |
| MAX WEIGHT       | 2.8KG                      |
| DIMENSIONS       | Ø127MM (OD) X 194MM (H)    |
| WEIGHT           | 5KG NET                    |

## OPTIONS

SUB-FIXTURE FOR HOLDING THE PARTS

VACUUM FIXTURE FOR WAFER LAPPING

*ENGIS IS ABLE TO DELIVER A COMPLETE SYSTEM TO FIT EACH CUSTOMER'S UNIQUE REQUIREMENTS  
AND OPTIMIZE THE MOST DEMANDING APPLICATIONS*

- HYPREZ COMPOSITE LAP PLATES
- DIAMOND AND COLLOIDAL LAPPING & POLISHING SLURRIES
- LUBRICANTS & CLEANERS
- POLISHING PADS/CLOTHS
- WAFER MOUNTING EQUIPMENT
- CONDITIONING RINGS



3465 Mainway, Unit #2  
Burlington, Ontario L7M 1A9  
Telephone: 905-632-3016  
[engiscanada@engis.com](mailto:engiscanada@engis.com)

[www.engisca.com](http://www.engisca.com)